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(54) **APPARATUSES INCLUDING ONE OR MORE SEMICONDUCTOR DEVICES AND RELATED SYSTEMS**

(52) **U.S. Cl.**

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(57)

ABSTRACT

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Related U.S. Application Data

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(51) **Int. Cl.**

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Memory devices may include a substrate supporting at least one semiconductor device thereon. The substrate may include an interface located proximate to an end of the substrate and sized, shaped, and configured to provide external electrical connection to the at least one semiconductor device. Hook-shaped engagement structures may be located proximate to, and laterally outward from, the interface, the engagement structures extending laterally beyond a longitudinal remainder of a lateral periphery of the substrate trailing the engagement structures. The end of the substrate may lack screw keep-outs. A carrier may include posts shaped, positioned, and configured to be positioned in throats of the hook-shaped engagement structures to secure the end of the substrate to the carrier. Sidewalls may extend longitudinally from a crossbar for placement along the remainder of the lateral periphery of the substrate.

